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S/N 10/775,656

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	YAMASHITA et al.	Examiner:	Tuan T. DINH
Serial No.:	10/775,656	Group Art Unit:	2841
Filed:	FEBRUARY 9, 2004	Docket No.:	10873.1397US01
Title:	ELECTRONIC COMPONENT BUILT-IN MODULE AND METHOD OF MANUFACTURING THE SAME		

CERTIFICATE UNDER 37 CFR 1.6(d):

I hereby certify that this paper is being transmitted by facsimile to the U.S. Patent and Trademark office on March 5, 2008.

By:

Name: Melc Cauffman

AMENDMENT AND RESPONSE

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the final Office Action mailed November 20, 2007, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims that begins on page 2 of this paper.

Remarks begin on page 7 of this paper.